

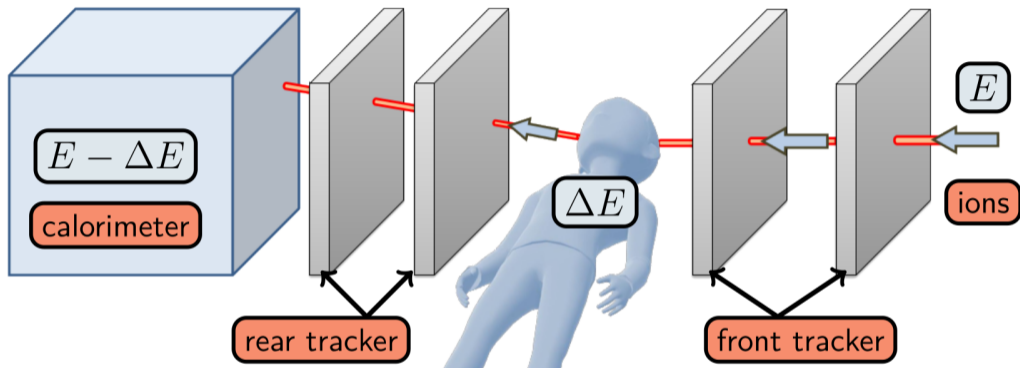
A high flux beam-telescope for ion radiography and imaging applications

M. Babeluk,
T. Bergauer, C. Imler

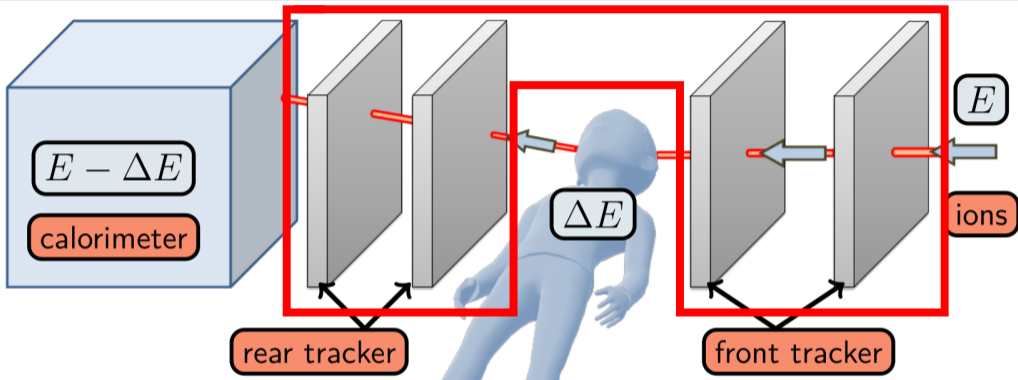
Institute for High Energy Physics - HEPHY

5th Ion Imaging Workshop 2024

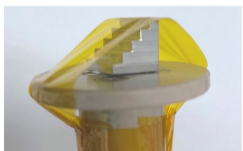
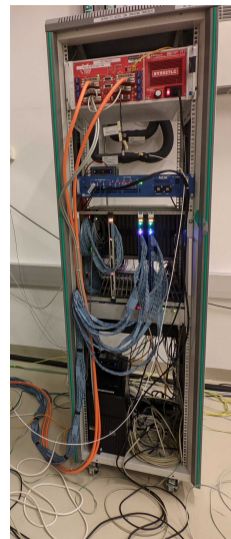
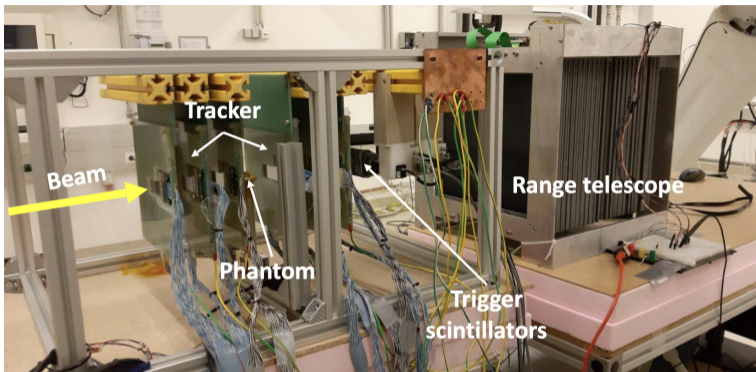
Oct 22nd 2024



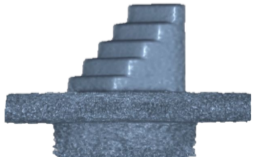
- A body part (our case phantom) exposed to the beam
- Incoming and outgoing trajectories measured via **tracker = beam telescope**
- Energy loss measured in calorimeter or Time of Flight detector



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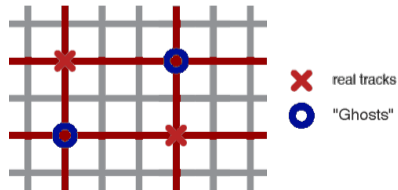
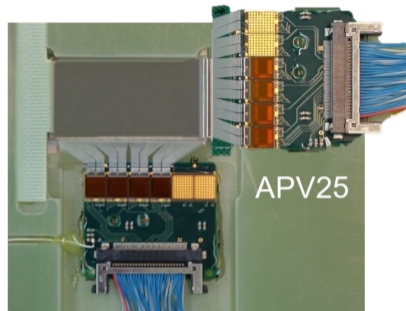
Phantom



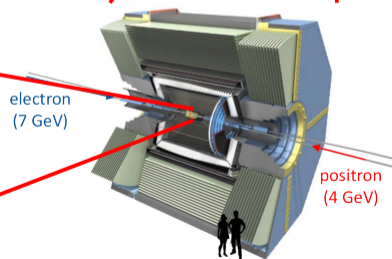
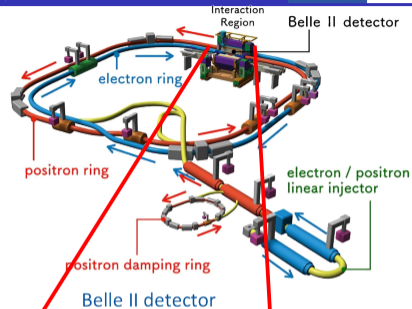
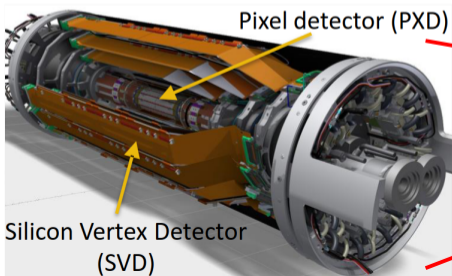
Reconstructed image

Readout electronics

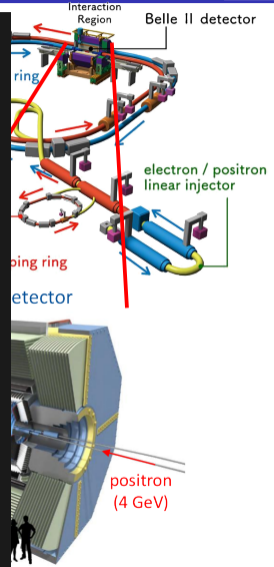
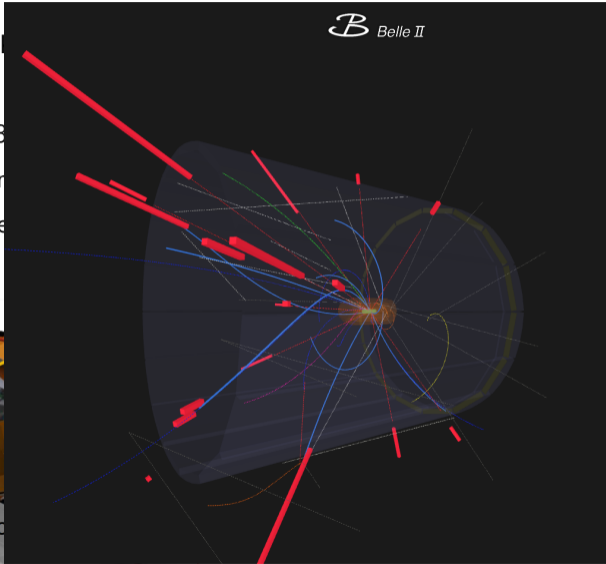
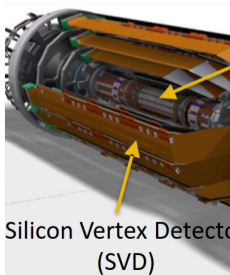
- Derived from current Belle II SVD detector
- Double sided silicon strip detectors:
- Designed at HEPHY for Belle SVD
- Manufactured by Micron
- Sensitive area: $5.1 \times 2.6 \text{ cm}^2$
- APV25 frontend chip and FADC backend
- Ambiguities at high particle fluxes ('Ghost hits')
- Not well scalable for larger detector area
- Max. readout speed: 30 kHz



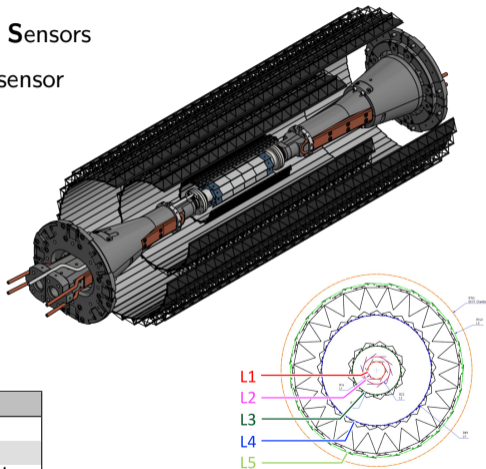
- Located at the SuperKEKB collider in Tsukuba/Japan
- Asymmetric $e^+ - e^-$ collisions
- $\sqrt{s} = M_{\Upsilon(4S)} = 10.58 \text{ GeV}$
- World record peak luminosity, exploring new physics
- Planned: further increase in luminosity



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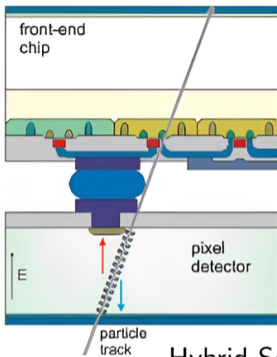


- Planned for LS2 ~ 2030, CDR published 2024
- 5 straight layers with **D**epleted **M**onolithic **A**ctive **P**ixel **S**ensors
- Identical chips on all layers: **O**ptimized **B**ELLE II **p**IXel sensor
- Different features enabled on different layers
- L1 & L2 (iVTX):**
 - All silicon ladders
 - Air cooling (constrains power)
- L3 to L5 (oVTX):**
 - Carbon fiber support frame
 - Cold plate with liquid cooling



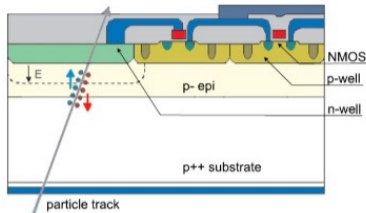
	L1	L2	L3	L4	L5	Unit
Radius	14.1	22.1	39.1	89.5	140.0	mm
# Ladders	6	10	8	18	26	
# Sensors	4	4	8	16	48	per ladder
Expected hitrate*	19.6	7.5	5.1	1.2	0.7	MHz/cm ²
Material budget	0.2	0.2	0.3	0.5	0.8	% X ₀

*: Large uncertainties due to beam background extrapolation, possible changes in IR (interaction region)

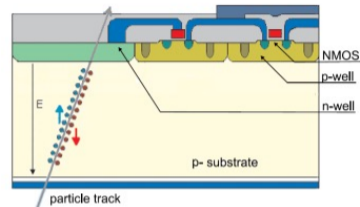


Hybrid Sensor

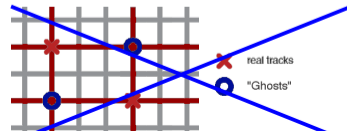
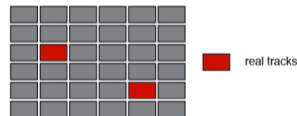
- Avoid error-prone bump or wire bonding in hybrid sensors
- Lower material budget: thinner sensor
- High granularity \Rightarrow high spatial resolution
- Higher hit rate capability \Rightarrow faster data talking



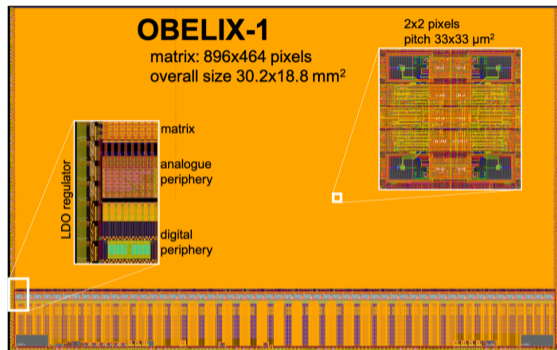
MAPS

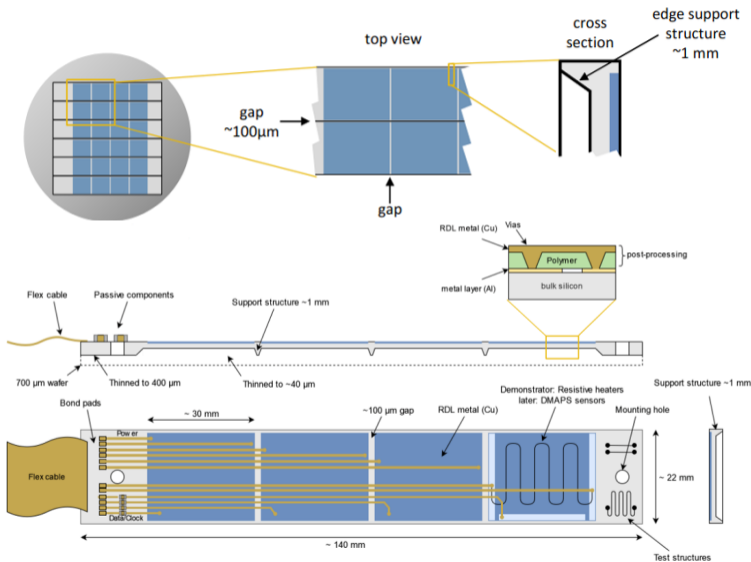


DMAPS

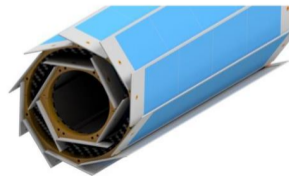


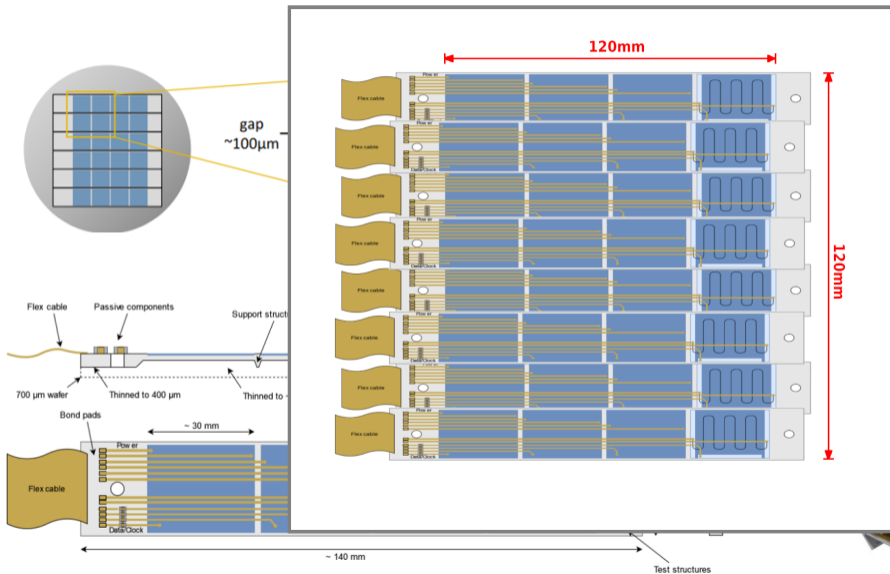
- 464 rows and 896 columns
- Sensitive area: $3.0 \times 1.5 \text{ cm}^2$
- Timestamp resolution: $\sim 50 \text{ ns}$
- Up to $10 \mu\text{s}$ trigger latency
- Power: $\sim 200 \text{ mW/cm}^2$
- TID tolerance: 1 MGy
- NIEL tolerance: $5 \times 10^{14} \text{ n}_{\text{eq}}/\text{cm}^2$
- Hit rates up to 120 MHz/cm^2
- Readout bandwidth $\sim 3 \text{ MHz}$
- Additional feature: Precision timing module ($\sim 2 \text{ ns}$)



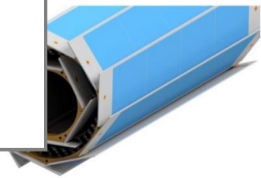


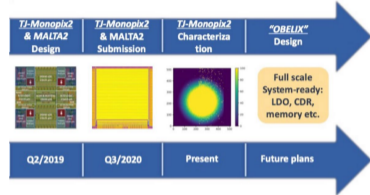
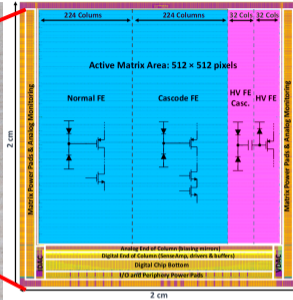
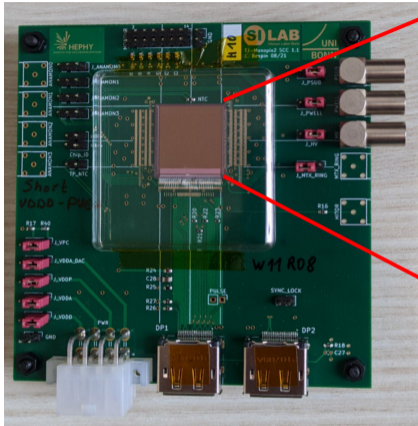
- iVTX: Innermost Two VTX Layers
- Self supported all-silicon ladders
- 4 Chips per iVTX ladder
- Sensitive area: $12 \times 1.5 \text{ cm}^2$
- Minimal material budget: $0.2\% X_0$
- Air cooling
- For a beam telescope: 'unrolled' iVTX for each plane thinkable





Innermost Two VTX Layers
 colored all-silicon ladders
 per iVTX ladder
 area: $12 \times 1.5 \text{ cm}^2$
 material budget: $0.2\% X_0$
 big
 m telescope: 'unrolled'
 each plane thinkable



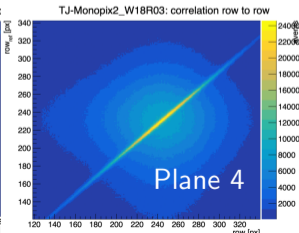
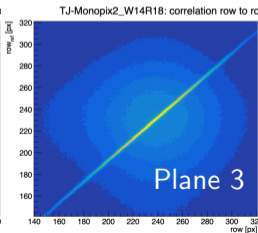
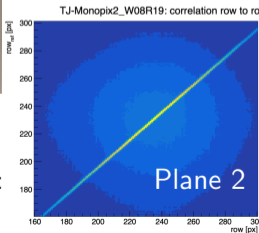


- Pixel Sensor - No 'Ghost hits'
- R&D chip with 4 frontend flavors
- Exclusive operation: blue or magenta region, not both
- TowerJazz 180 nm imaging process
- Sensitive area: $1.7 \times 1.7 \text{ cm}^2$, $512 \times 512 \text{ cm}^2$
- Pixel size: $33.04 \times 33.04 \mu\text{m}^2$, Timestamping 25 ns



- First test at MedAustron April 2024
- ⇒ Just to test the setup
- Telescope kept synchronization, very nice correlations
- Many data overflows: Bug in software found
- Caused inefficient processing on PC ⇒ data loss (overflow)
- Another test needed to test the fix (under planning)

Correlation: Plane 1 with:



Parameter	Current Tracker	TJ-Monopix2	OBELIX
Recordable hitrate	0.03 MHz	~ 0.5 MHz	~ 3 MHz
Hitrate tolerance		0.5 MHz	120 MHz/cm ²
Sensitive area	5.1 × 2.6 cm ²	1.7 × 1.7 cm ²	3.0 × 1.5 cm ²
Channels	(strips) 512 × 512	(pixels) 512 × 512	(pixels) 896 × 464
Resolution	29 × 14 μm ²	9.5 × 9.5 μm ²	9.5 × 9.5 μm ²
Pitch	100 × 50 μm ²	33 × 33 μm ²	33 × 33 μm ²

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100x faster data taking

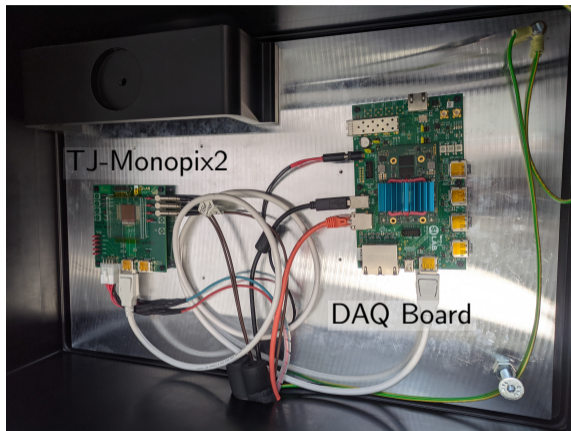
3x smaller area

3x/1.5x better resolution

- Factor 100 increased data rate capability
- ⇒ Previously 8 hour data taking reduced to 5 minutes (!)
- Smaller area covered with OBELIX telescope ⇒ but tiling possible
- Better spatial resolution (better than 10 μm)
- High hitrate tolerance allows upstream mixed-beam operation with selective trigger

- DMAPS technology promises great advantages in ion radiography
- First tests with the TJ-Monopix2 R&D chip are promising
- More tests are needed to test tracking and efficiency
- The OBELIX chip will be well suited for a beam telescope
- OBELIX Development and verification is entering final stage
- Aiming submission early 2025

Backup slides



- One DAQ board can connect to up to two chips
- DAQ Board connects to PC and Trigger Logic Unit (TLU)

OBELIX-1

IO Pads and Regulators

Analog

Pixel Matrix
896 Columns, 464 Rows

Analog EoC & Buffers

Regulator
Ctrl

IDACs &
VDACs

Monitoring
ADC

Temperature
Sensors

PowerOn
Reset

Digital Periphery

TRU (Trigger Unit)

TRG0 (Trigger Group)

EoC0 EoC1 EoC2 EoC3

Stage 1 Memory

Stage 2 Memory

TRG1 (Trigger Group)

EoC0 EoC1 EoC2 EoC3

Stage 1 Memory

Stage 2 Memory

...

TRG111 (Trigger Group)

EoC0 EoC1 EoC2 EoC3

Stage 1 Memory

Stage 2 Memory

PTD

CRU
(Control Unit)

SCU
(Sync Clock Unit)

TXU
(Transmission Unit)

TTT
(Track Trigger Transmission)

Analog:

- Column drain architecture
- Monitoring ADC
- Temperature sensors

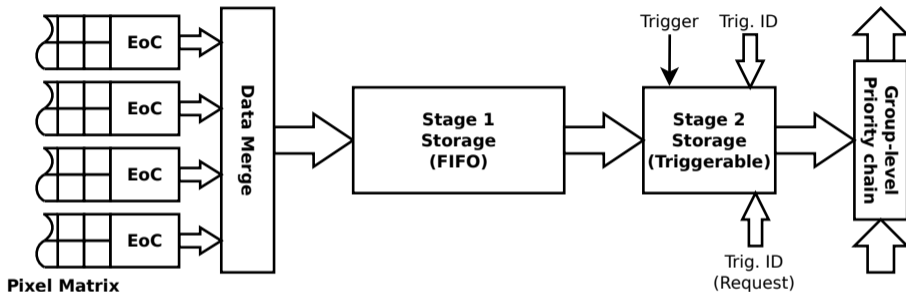
Power:

- On-chip LDOs

Digital:

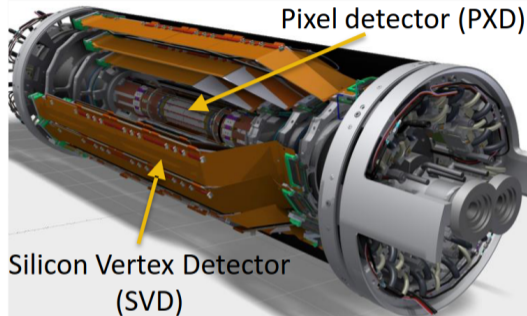
- TRU: Pixel readout, trigger processing
- PTD: Part of TRU for precision timing
- TTT: Fast transmission in parallel for contribution to Belle II Trigger

OBELIX Trigger Group (TRG)



- Trigger memory: 112 Trigger Groups, for 8 columns each
- Sophisticated 2 stage memory design
- Stage 1: Pre-trigger buffer **SRAM**, low power
- Stage 2: **Associative memory** to match trigger, power hungry
- Buffer sizing driven by power and hitrate, evaluated with extensive simulations

- Two technology system
- PXD:
 - 2 Layers of DEPFET pixel sensor
 - $\sim 10 \mu\text{m}$ spatial resolution
 - 20 μs integration time
 - ⇒ Cannot contribute to track finding
 - See [PXD Talk](#) from Jannes Schmitz
- SVD:
 - 4 layers of double sided strip sensor
 - 3 ns Cluster time resolution
 - 3% Occupancy limit (6% with hit-time reconstruction + BG rejection)
 - Expected occupancy up to 4.7% after LS2 (large uncertainty)
 - ⇒ Little safety margin in occupancy
 - ⇒ Trigger latency limited to 5 μs by SVD readout
 - See [SVD Talk](#) from Alice Gabrielli



1. High hit efficiency at demanding hitrates with sufficient timesampling



- Matrix inherited from TJ-Monopix2
- See [CMOS Talk](#) from Lars Schall

2. Handling trigger latency of the Belle II experiment (up to 10 μ s)



- New implementation of digital periphery
- Simulation to validate performance

3. Power dissipation:

- air cooling of inner layers
- liquid cooling of outer layers



- Optimized digital logic with optional features

4. Little space for cables inside detector



- On chip voltage regulators
- 2 LVDS downlinks for groups of chips (Rx)
- 1 or 2 LVDS uplink(s) per chip (Tx)

5. Increased timing resolution at expense of power



- Precision timing module in periphery (PTD)
- Offline timing annotation

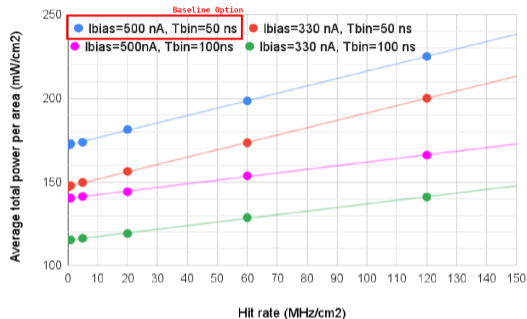
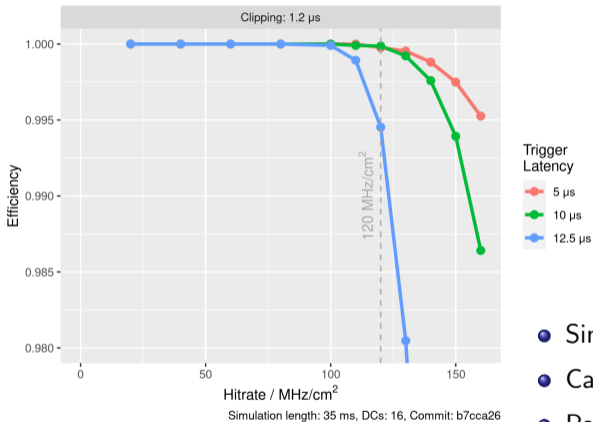
6. Contribution to Belle II Trigger



- Independent fast data path
- Fast coarse hit transmission

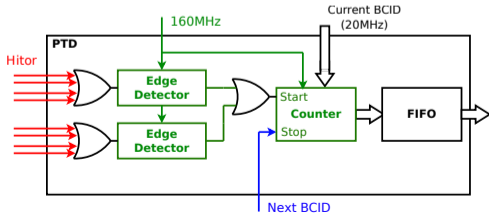
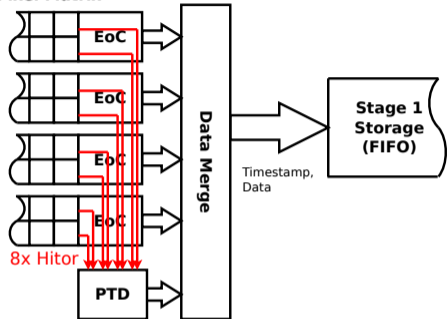
These features require significant power:
Only switched on for liquid cooled layers L3 to L5

TRU Performance



- Simulation includes: clustering & charge/ToT conversion
- Calibrated with TJ-Monopix2 results
- Power 10% above budget for 120 MHz/cm²
- Clock frequency or analog bias current could be reduced

Pixel Matrix



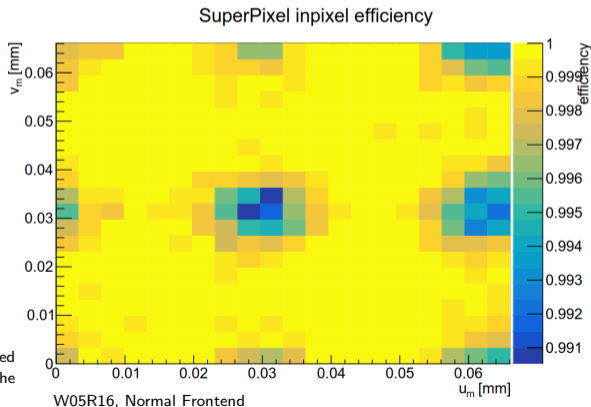
- Hitor: all comparator outputs of one column in an OR-chain (asynchronous)
- PTD: precision timing better than Timestamp (50 ns)
- Sampling: 2.95 ns period (169.7 MHz DDR)
- Power hungry feature: disabled in iVTX
- Little overhead when disabled (Little die space, clock can be turned off)
- Resolution limited by timewalk and PVT (process, voltage, temperature) variation
- Calibration necessary

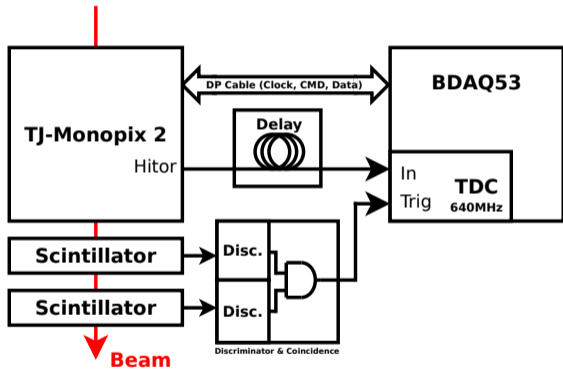
- First week: Regular measurements with telescope (efficiency and angular scans for depletion)
- Second week: Timing measurements, parasitic to RD50 MPW3 Testbeam
- Beamtelescope with Alpide chips (Duranta)
- Spatial Resolution $< 10 \mu\text{m}$ for all chips

Chip SN	Irradiation	Substrate
W02R05	None	Epi
W05R16	ρ^+ , $5 \times 10^{14} \text{ n}_{\text{eq}}$	Epi
W08R19	None	Epi
W14R12	None	Cz

Chip SN	Frontend	Efficiency
W05R16	Normal	0.9999
	Normal Cascode	0.9979
	HV Cascode	0.9913
	HV	0.9811

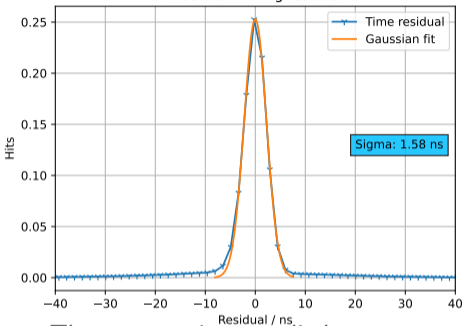
The measurements leading to these and following results have been performed at the Test Beam Facility at DESY Hamburg (Germany), a member of the Helmholtz Association (HGF).





- TDC module of BDAQ53 firmware measures delay between scintillator and Hitor
- TDC words inserted into data stream
- TDC data is matched to hits offline
- Whole chip has one Hitor line: ambiguities arise
- ToT is measured by both, TJ-Monopix2 and TDC module
- Therefore used to match and cut (± 25 ns cut)

W08R19: Timing residual



- Three corrections applied:

- Column delay (Hitor)
- Row delay (Hitor)
- Timewalk

- Tail in distribution: wrong associations

- Resolution: < 2 ns (unirradiated), < 3 ns (irradiated W05R16)

N: Timing accuracy

